



Material Content Data Sheet



Sales Product Name	TLE7718G			Issued	17. April 2015			
MA#	MA001356176							
Package	PG-DSO-52-4			Weight*	872.01 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	27.549	3.16	3.16	31592	31592
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		84	
	non noble metal	zinc	7440-66-6	0.293	0.03		336	
	non noble metal	iron	7439-89-6	5.854	0.67		6713	
wire	non noble metal	copper	7440-50-8	237.701	27.26	27.97	272591	279724
	noble metal	gold	7440-57-5	3.083	0.35	0.35	3536	3536
	encapsulation	organic material	carbon black	1333-86-4	1.163	0.13		1333
encapsulation	plastics	epoxy resin	-	53.484	6.13		61334	
	inorganic material	silicondioxide	60676-86-0	526.700	60.41	66.67	604009	666676
leadfinish	non noble metal	tin	7440-31-5	7.602	0.87	0.87	8718	8718
plating	noble metal	silver	7440-22-4	0.968	0.11	0.11	1110	1110
glue	plastics	epoxy resin	-	1.885	0.22		2161	
	noble metal	silver	7440-22-4	5.654	0.65	0.87	6483	8644
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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